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MICON 5, SMT low, 5,5 N, 1 NO



fields of application

- > Measurement-control-regulation
- > Mechanical and system engineering
- > Automotive
- > Electro-medical

special features

- Gold contacts, reliable switching with low currents
- > Special tactile feedback
- > High packing density due to small form factor (5.1 x 6.4 mm)
- > Different operating forces
- > Ring and full illumination of the button surface due to plunger
- > Variable overall heights due to plunger
- > Terminal technology: SMT
- > Traceability through product identification in accordance with DIN EN ISO 9001

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description

MICON 5 tactile switches offer extreme switching reliability, with a very small space requirement. They can be arranged individually, in rows or as key blocks. For use beneath overlays, we recommend combining the MICON 5 key switches with plungers. Here are the properties at a glance:

- > Suitable for the most important soldering techniques
- > Soldering bath for THT versions
- > Reflow soldering for SMT versions
- > Vapor phase soldering for SMT versions
- > Manual soldering
- > Processing of the SMT design with SMT automatic assembly machines
- > IMDS entry

MICON 5, SMT nieder mit einer Bauhöhe von nur 3,45 mm Verarbeitungshinweis: Sonderpipette (Siemens Siplace Best.-Nr. 348514-02) Bestückung mit Revolverkopf. Vorschlag für Schablonendruck: 150 ?m-Schablone mit 10% Pad-Verkleinerung auf Fläche

technical data

y general		
Operating temperature, min.	-40 °C	
Storage temperature, min.	-40 °C	
Operating temperature, max.	90 °C	
Storage temperature, max.	90 °C	
illuminated	No	
Soldering	Reflow	

The information in this data sheet only contains general descriptions and / or performance features, which may not apply precisely as described to the respective application, and which my change due to further product enhancements. The technical data, illustrations and other information about our products are the mere results of individual technical testing. These descriptions and other product features are only binding if they expressly agreed upon at the time of the conclusion of a binding contract. In all other cases, we reserve the right to make technical changes as well as changes of availability. Pictures and other graphic illustrations are approximations only. All product names may be trademarks or brand names of the RAFI Group or any other sub-supplier of RAFI. The use of such by any third parties for their own purposes may infringe the rights of the respective entity holding those rights.

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Solder heat resistance according DIN EN 60068-2-58 to standard DIN EN 61760-1

Packaging Blister
Packaging unit 2,100 pcs.
net weight 0.3 g

Operating life 1,000,000 cycles B10 1,300,000 cycles

Shock resistance according to 100 g at 6 ms amplitude semi-sinusoidal

standard IEC 60068-2-27

oscillation restistance according 5 g at 10...500 Hz

to standard IEC 60068-2-6

MOQ order 2,100 pcs.

RoHS compliant Yes

REACH compliant Yes

Component material Silicon

> mounting diameters

Installation height 3.45 mm

Grid, min. 6 x 7,8 mm

Outside dimension, length 6.4 mm

Outside dimension, width 5.1 mm

Outside dimension, height 3.45 mm

> mechanical data

Actuation function momentary contact function

Operating force, max. 8 N
Operating force, min. 5,5 N
Switching travel 0.7 mm
Contact function 1 NO

Contact system Snap-action contact

Contact material Gold
Terminal on the rear SMT
Solderability Yes

> electrical data

Rated voltage, min.

Rated voltage, max.

Dielectric strength

Rated current, min.

Rated current, max.

O.1 A

Rated power, max.

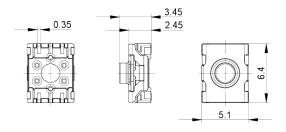
0.1 W

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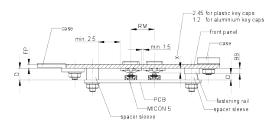


drawings

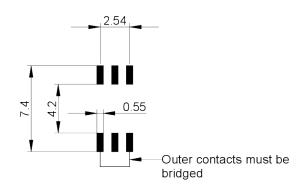
Dimensioned drawing



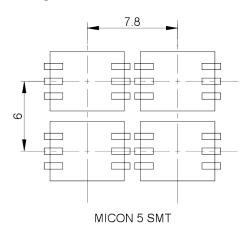
System drawing



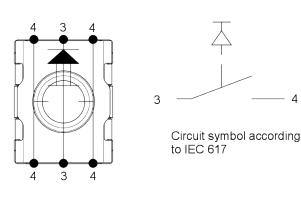
PCB drawing



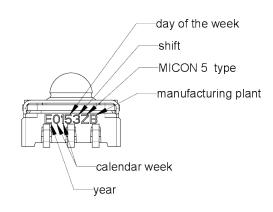
PCB drawing



Schematic diagram



Product labeling drawing



Packaging drawing

